

# IRG4IBC20KDPbF

INSULATED GATE BIPOLAR TRANSISTOR WITH  
 ULTRAFAST SOFT RECOVERY DIODE

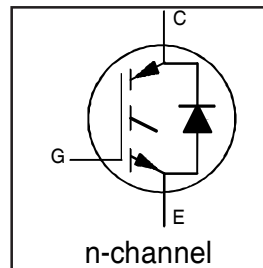
Short Circuit Rated  
 UltraFast IGBT

## Features

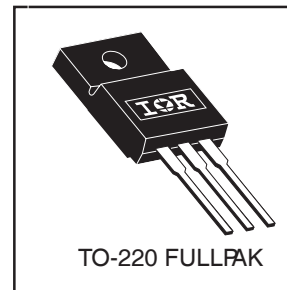
- High switching speed optimized for up to 25kHz with low  $V_{CE(on)}$
- Short Circuit Rating 10 $\mu$ s @ 125°C,  $V_{GE} = 15V$
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than previous generation
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft-recovery anti-parallel diodes for use in bridge configurations
- Industry standard TO-220 FULLPAK
- Lead-Free

## Benefits

- Generation 4 IGBTs offer highest efficiencies available maximizing the power density of the system
- IGBTs optimized for specific application conditions
- HEXFRED™ diodes optimized for performance with IGBTs. Minimized recovery characteristics reduce noise EMI
- Designed to exceed the power handling capability of equivalent industry-standard IGBTs



$V_{CES} = 600V$   
 $V_{CE(on)} \text{ typ.} = 2.27V$   
 @  $V_{GE} = 15V, I_C = 6.3A$



## Absolute Maximum Ratings

	Parameter	Max.	Units
$V_{CES}$	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	11.5	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	6.3	
$I_{CM}$	Pulsed Collector Current ①	23	
$I_{LM}$	Clamped Inductive Load Current ②	24	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	6.3	
$I_{FM}$	Diode Maximum Forward Current	24	
$t_{sc}$	Short Circuit Withstand Time	10	$\mu$ s
$V_{ISOL}$	RMS Isolation Voltage, Terminal to Case, $t = 1 \text{ min}$	2500	V
$V_{GE}$	Gate-to-Emitter Voltage	$\pm 20$	W
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	34	
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	14	
$T_J$	Operating Junction and	-55 to +150	$^\circ C$
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw.	10 lbf•in (1.1 N•m)	

## Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case - IGBT	—	3.7	$^\circ C/W$
$R_{\theta CS}$	Junction-to-Case - Diode	—	5.5	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	—	65	
$Wt$	Weight	2.0 (0.07)	—	g (oz)

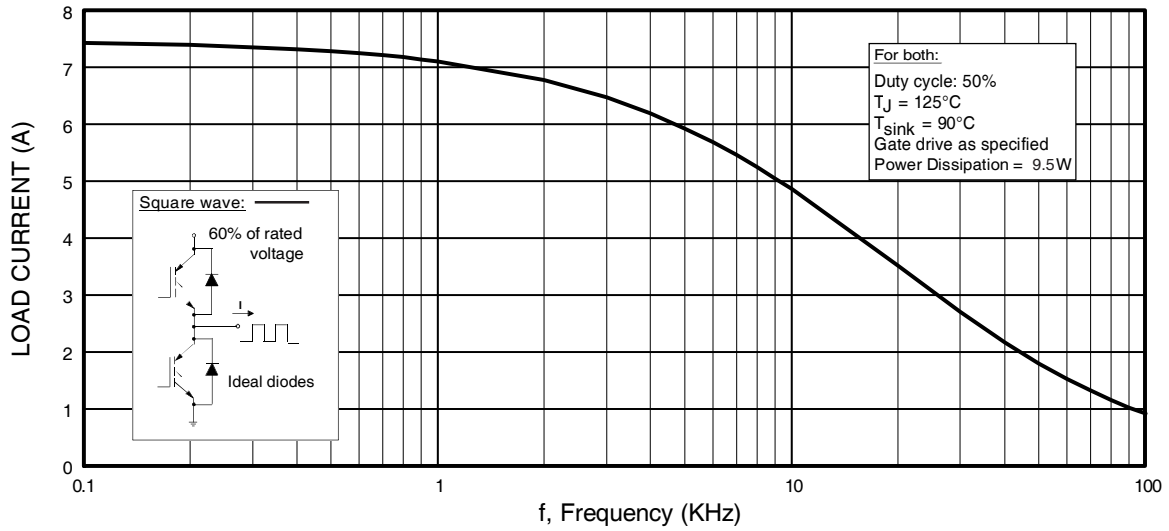
# IRG4IBC20KDPbF

## Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

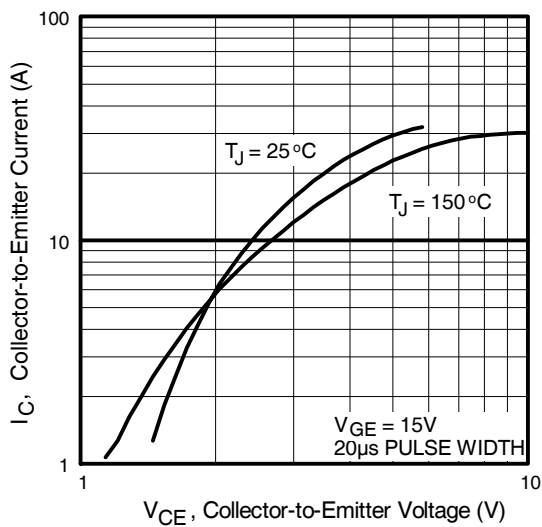
	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage <sup>③</sup>	600	—	—	V	$V_{GE} = 0V, I_C = 250\mu A$
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	0.49	—	V/°C	$V_{GE} = 0V, I_C = 1.0mA$
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	2.27	2.8	V	$I_C = 9.0A$ $V_{GE} = 15V$ See Fig. 2, 5
		—	3.01	—		
		—	2.43	—		
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	6.0		$V_{CE} = V_{GE}, I_C = 250\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-10	—	mV/°C	$V_{CE} = V_{GE}, I_C = 250\mu A$
$g_{fe}$	Forward Transconductance <sup>④</sup>	2.9	4.3	—	S	$V_{CE} = 100V, I_C = 9.0A$
$I_{CES}$	Zero Gate Voltage Collector Current	—	—	250	$\mu A$	$V_{GE} = 0V, V_{CE} = 600V$ $V_{GE} = 0V, V_{CE} = 600V, T_J = 150^\circ\text{C}$
		—	—	1000		
$V_{FM}$	Diode Forward Voltage Drop	—	1.4	1.7	V	$I_C = 8.0A$ See Fig. 13
		—	1.3	1.6		
$I_{GES}$	Gate-to-Emitter Leakage Current	—	—	$\pm 100$	nA	$V_{GE} = \pm 20V$

## Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

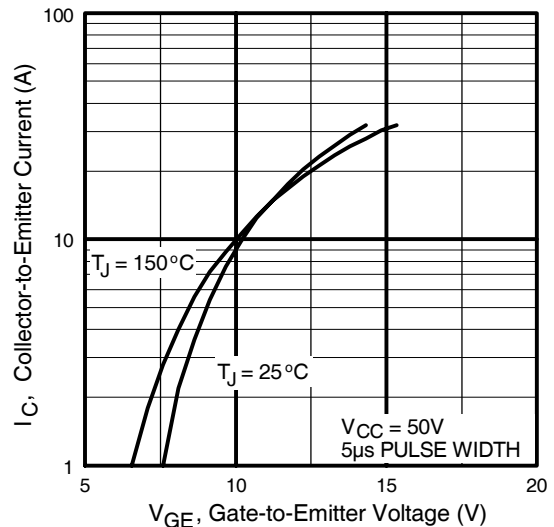
	Parameter	Min.	Typ.	Max.	Units	Conditions
$Q_g$	Total Gate Charge (turn-on)	—	34	51	nC	$I_C = 9.0A$ $V_{CC} = 400V$ $V_{GE} = 15V$ See Fig.8
$Q_{ge}$	Gate - Emitter Charge (turn-on)	—	4.9	7.4		
$Q_{gc}$	Gate - Collector Charge (turn-on)	—	14	21		
$t_{d(on)}$	Turn-On Delay Time	—	54	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 9.0A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 50\Omega$
$t_r$	Rise Time	—	34	—		
$t_{d(off)}$	Turn-Off Delay Time	—	180	270		
$t_f$	Fall Time	—	72	110		
$E_{on}$	Turn-On Switching Loss	—	0.34	—	mJ	Energy losses include "tail" and diode reverse recovery See Fig. 9,10,14
$E_{off}$	Turn-Off Switching Loss	—	0.30	—		
$E_{ts}$	Total Switching Loss	—	0.64	0.96		
$t_{sc}$	Short Circuit Withstand Time	10	—	—	$\mu s$	$V_{CC} = 360V, T_J = 125^\circ\text{C}$ $V_{GE} = 15V, R_G = 50\Omega, V_{CPK} < 500V$
$t_{d(on)}$	Turn-On Delay Time	—	51	—	ns	$T_J = 150^\circ\text{C}$ , See Fig. 10,11,14 $I_C = 9.0A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 50\Omega$
$t_r$	Rise Time	—	37	—		
$t_{d(off)}$	Turn-Off Delay Time	—	220	—		
$t_f$	Fall Time	—	160	—		
$E_{ts}$	Total Switching Loss	—	0.85	—	mJ	Energy losses include "tail" and diode reverse recovery
$L_E$	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package
$C_{ies}$	Input Capacitance	—	450	—	pF	$V_{GE} = 0V$ $V_{CC} = 30V$ See Fig. 7 $f = 1.0MHz$
$C_{oes}$	Output Capacitance	—	61	—		
$C_{res}$	Reverse Transfer Capacitance	—	14	—		
$t_{rr}$	Diode Reverse Recovery Time	—	37	55	ns	$T_J = 25^\circ\text{C}$ See Fig. 14 $T_J = 125^\circ\text{C}$ 14
		—	55	90		
$I_{rr}$	Diode Peak Reverse Recovery Current	—	3.5	5.0	A	$T_J = 25^\circ\text{C}$ See Fig. 15 $T_J = 125^\circ\text{C}$ 15
		—	4.5	8.0		
$Q_{rr}$	Diode Reverse Recovery Charge	—	65	138	nC	$T_J = 25^\circ\text{C}$ See Fig. 16 $T_J = 125^\circ\text{C}$ 16
		—	124	360		
$di_{(rec)M}/dt$	Diode Peak Rate of Fall of Recovery During $t_b$	—	240	—	A/ $\mu s$	$T_J = 25^\circ\text{C}$ See Fig. 17 $T_J = 125^\circ\text{C}$ 17
		—	210	—		



**Fig. 1** - Typical Load Current vs. Frequency  
 (Load Current =  $I_{\text{RMS}}$  of fundamental)

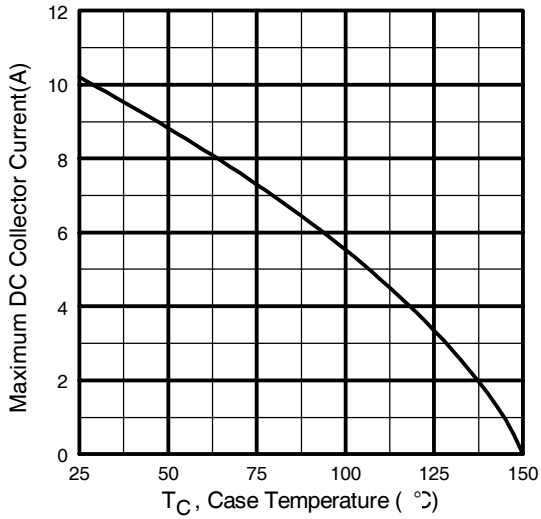


**Fig. 2** - Typical Output Characteristics

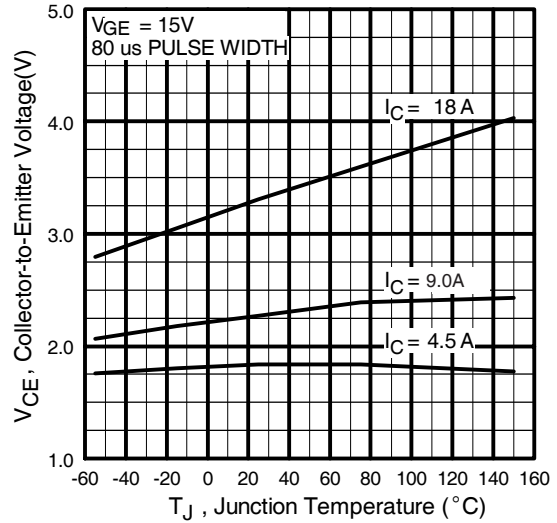


**Fig. 3** - Typical Transfer Characteristics

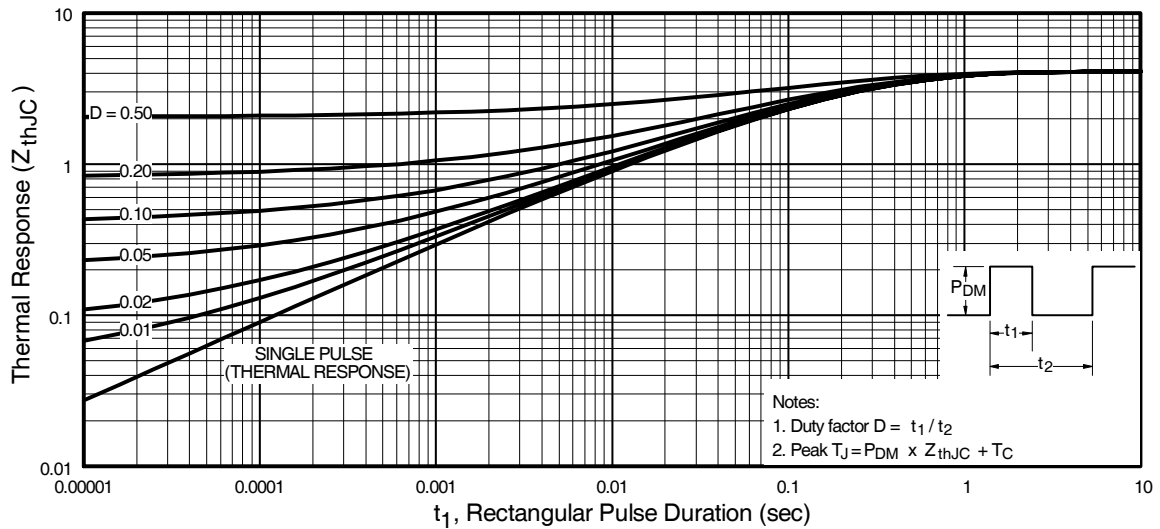
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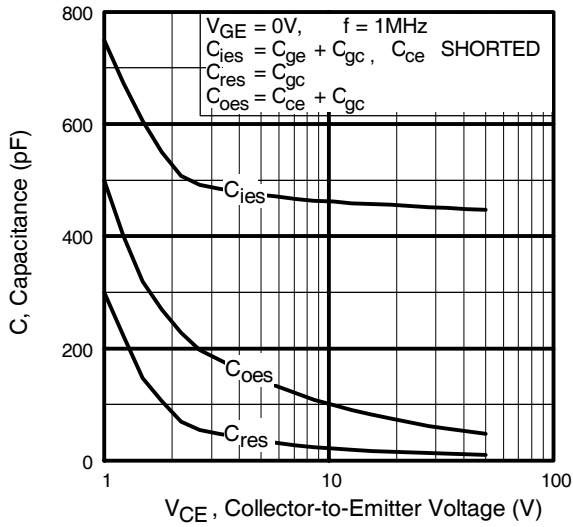
**Fig. 4** - Maximum Collector Current vs. Case Temperature



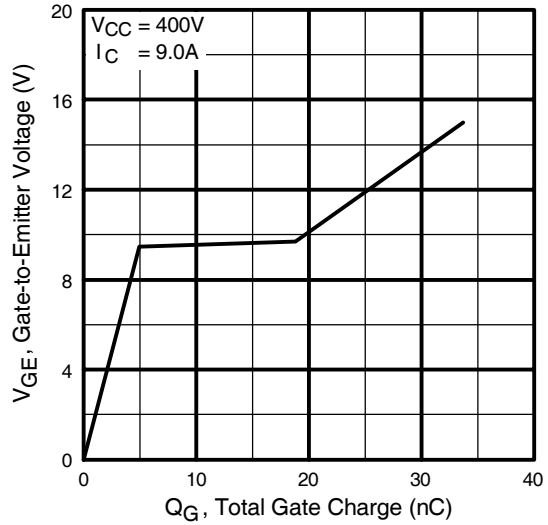
**Fig. 5** - Typical Collector-to-Emitter Voltage vs. Junction Temperature



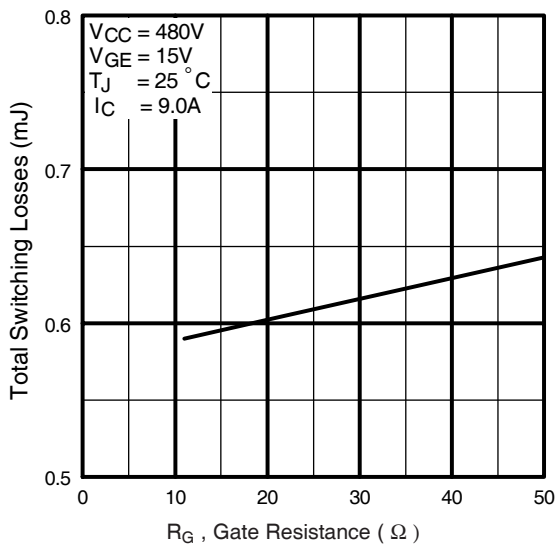
**Fig. 6** - Maximum Effective Transient Thermal Impedance, Junction-to-Case



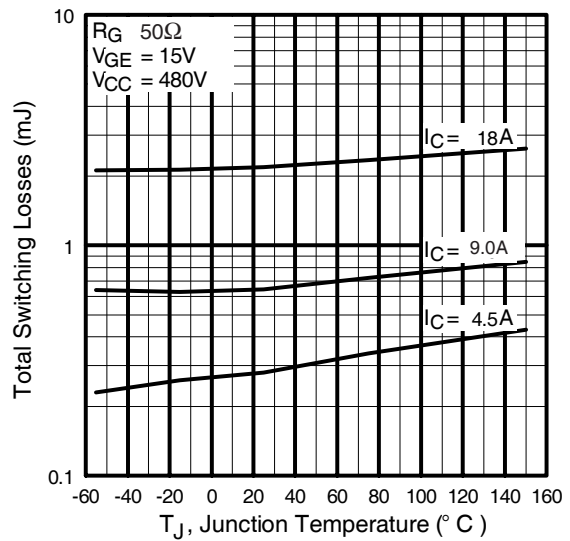
**Fig. 7** - Typical Capacitance vs. Collector-to-Emitter Voltage



**Fig. 8** - Typical Gate Charge vs. Gate-to-Emitter Voltage

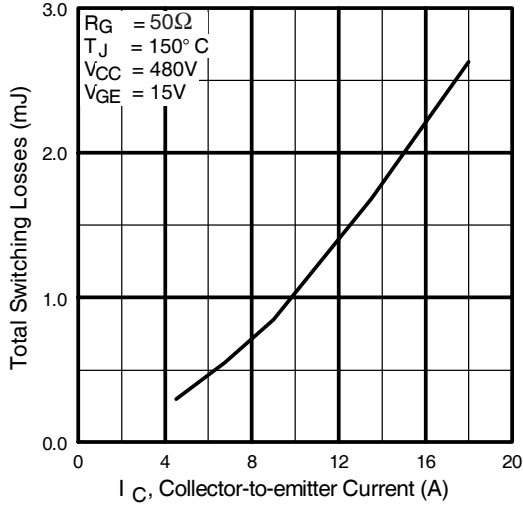


**Fig. 9** - Typical Switching Losses vs. Gate Resistance

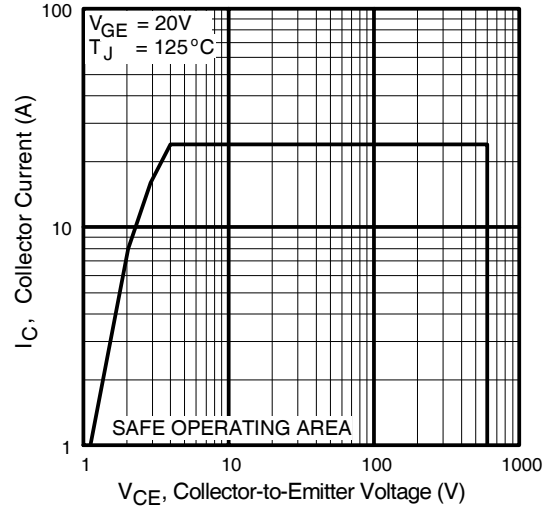


**Fig. 10** - Typical Switching Losses vs. Junction Temperature

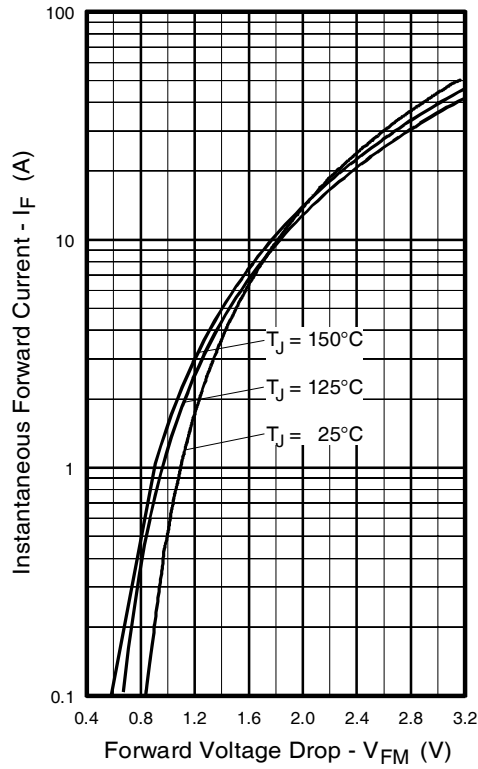
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**Fig. 11** - Typical Switching Losses vs. Collector-to-Emitter Current



**Fig. 12** - Turn-Off SOA



**Fig. 13** - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

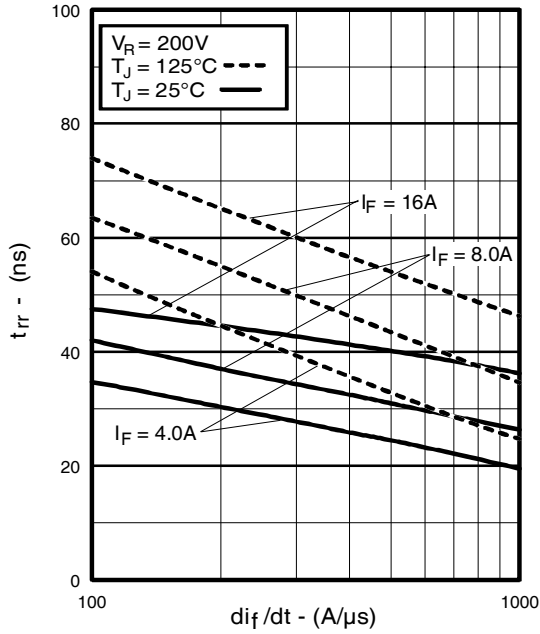


Fig. 14 - Typical Reverse Recovery vs.  $di_f/dt$

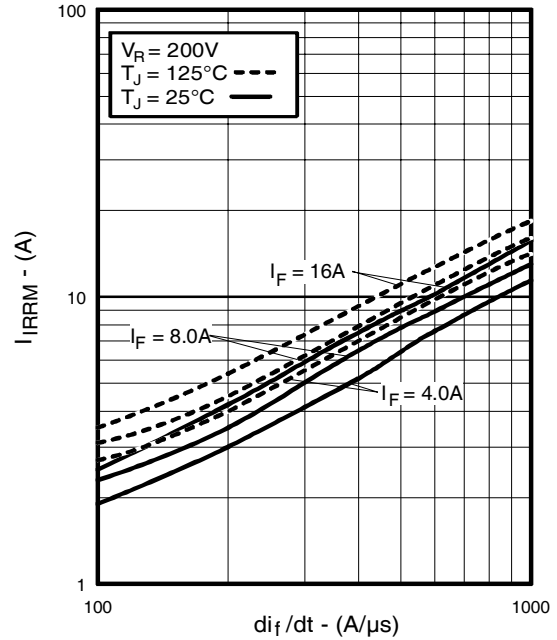


Fig. 15 - Typical Recovery Current vs.  $di_f/dt$

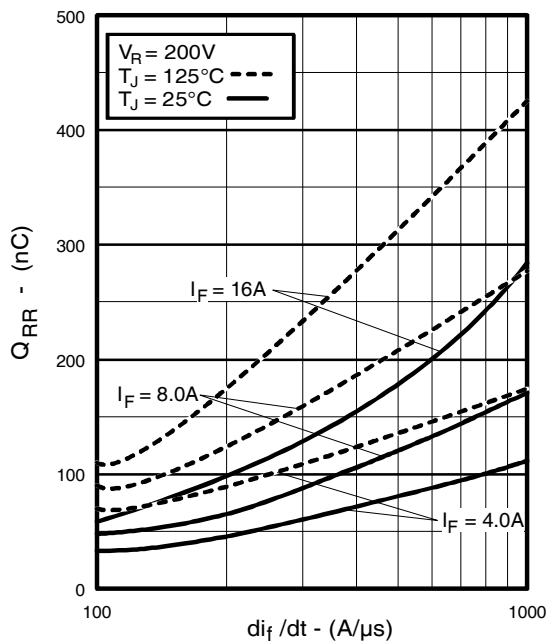


Fig. 16 - Typical Stored Charge vs.  $di_f/dt$

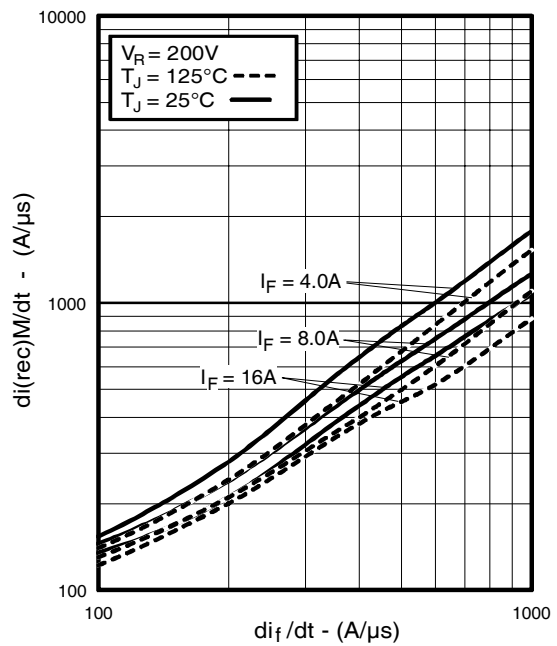
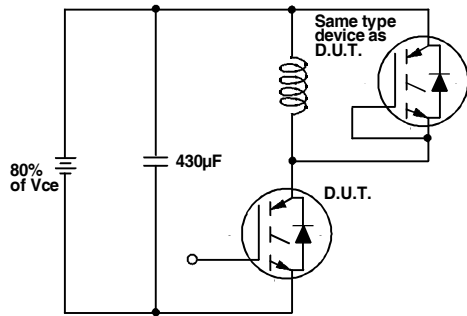
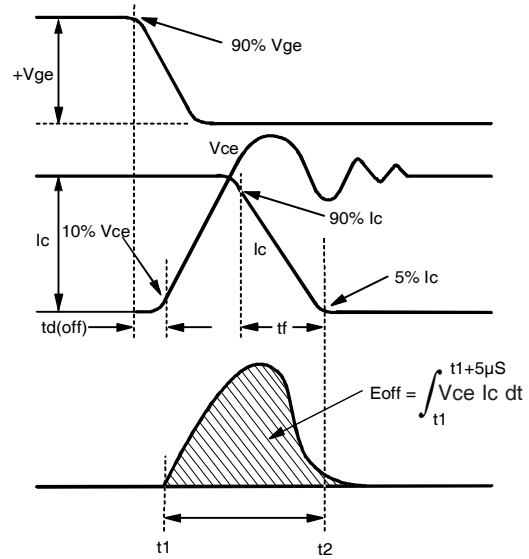


Fig. 17 - Typical  $di_{(rec)M}/dt$  vs.  $di_f/dt$

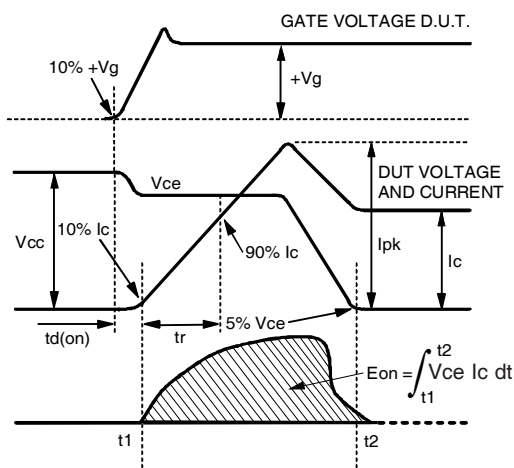
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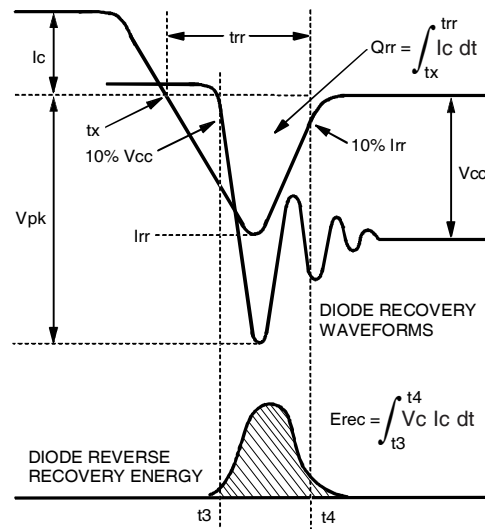
**Fig. 18a** - Test Circuit for Measurement of  $I_{LM}$ ,  $E_{on}$ ,  $E_{off}(\text{diode})$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$ ,  $t_{d(on)}$ ,  $t_r$ ,  $t_{d(off)}$ ,  $t_f$



**Fig. 18b** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{off}$ ,  $t_{d(off)}$ ,  $t_f$



**Fig. 18c** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{on}$ ,  $t_{d(on)}$ ,  $t_r$



**Fig. 18d** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{rec}$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$



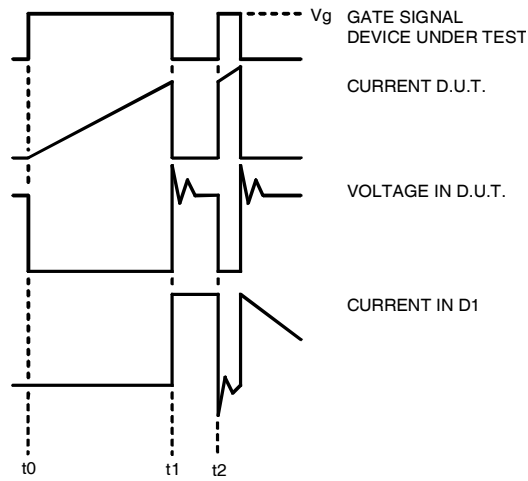


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

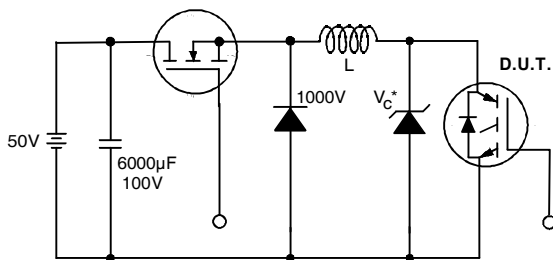


Figure 19. Clamped Inductive Load Test Circuit

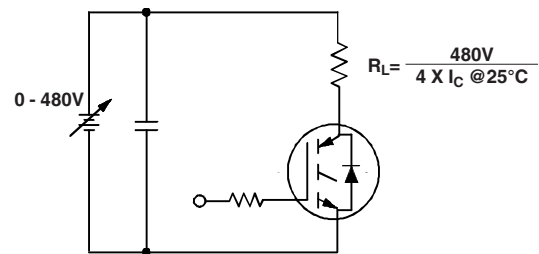


Figure 20. Pulsed Collector Current Test Circuit

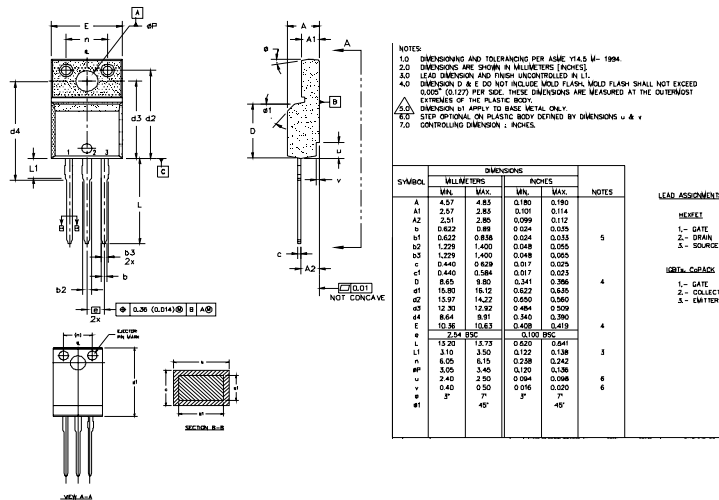
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## Notes:

- ① Repetitive rating:  $V_{GE}=20V$ ; pulse width limited by maximum junction temperature (figure 20)
- ②  $V_{CC}=80\%(V_{CES})$ ,  $V_{GE}=20V$ ,  $L=10\mu H$ ,  $R_G=50\Omega$  (figure 19)
- ③ Pulse width  $\leq 80\mu s$ ; duty factor  $\leq 0.1\%$ .
- ④ Pulse width  $5.0\mu s$ , single shot.

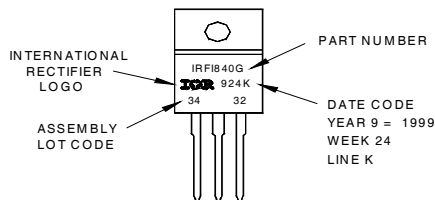
## TO-220 Full-Pak Package Outline

Dimensions are shown in millimeters (inches)



## TO-220 Full-Pak Part Marking Information

EXAMPLE: THIS IS AN IRF1840G  
 WITH ASSEMBLY  
 LOT CODE 3432  
 ASSEMBLED ON WW 24 1999  
 IN THE ASSEMBLY LINE "K"  
**Note:** "P" in assembly line position indicates "Lead-Free"



Data and specifications subject to change without notice.